L	Hits	Search Text	DB	Time stamp
Number 1	307097	has with /sinh spenden lid sorron	USPAT;	2004/08/30
1	30/09/	heat with (sink spreader lid cover dissipate dissipation dissipated	US-PGPUB;	10:05
		dissipated slug frame radiate radiating	EPO; JPO;	10.03
		radiated)	DERWENT;	
			IBM TDB	i
2	2581220	semiconductor die dice chip ic	USPAT;	2004/08/30
		(integrated adj circuit)	US-PGPUB;	10:06
-			EPO; JPO;	
			DERWENT;	
	2724007		IBM_TDB	2224 /22 /22
3	3734087	1	USPAT;	2004/08/30
		printed circuit) adj "4" board)	US-PGPUB;	10:07
			EPO; JPO; DERWENT;	
			IBM TDB	
4	106697	(thermally thermal) adj6 (isolated	USPAT;	2004/08/30
-		insulated insulation insulate insulating)	US-PGPUB;	11:41
		<u> </u>	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	390		USPAT;	2004/08/30
		dissipate dissipation dissipated	US-PGPUB;	11:41
		dissipated slug frame radiate radiating	EPO; JPO;	
		radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same	DERWENT; IBM TDB	
		(substrate board carrier pcb ((wiring	LPM_IDP	
		printed circuit) adj "4" board)) same		
		((thermally thermal) adj6 (isolated		
		insulated insulation insulate		
		insulating))		
6	5080	(thermally thermal) adj6 (isolated)	USPAT;	2004/08/30
			US-PGPUB;	11:41
			EPO; JPO;	
			DERWENT;	
7	390	 (heat with (sink spreader lid cover	IBM_TDB	2004/09/20
['	390	dissipate dissipation dissipated	USPAT; US-PGPUB;	2004/08/30
		dissipated slug frame radiate radiating	EPO; JPO;	11.45
İ		radiated)) same (semiconductor die dice	DERWENT;	
1		chip ic (integrated adj circuit)) same	IBM TDB	
		(substrate board carrier pcb ((wiring	_	
		printed circuit) adj "4" board)) same		
		((heat with (sink spreader lid cover		
		dissipate dissipation dissipated		
		dissipated slug frame radiate radiating radiated)) same (semiconductor die dice		
		chip ic (integrated adj circuit)) same		
		(substrate board carrier pcb ((wiring		
		printed circuit) adj "4" board)) same		
		((thermally thermal) adj6 (isolated		
		insulated insulation insulate		
		insulating)))		

	· · · · · · · · · · · · · · · · · · ·			
8	0	((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulating)))) not ((heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulation insulate insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:42
10	0	dissipate dissipation dissipated dissipated slug frame radiate radiating radiated) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated))) not ((heat with (sink spreader lid cover dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same ((thermally thermal) adj6 (isolated insulated insulate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:43
9	45	insulating))) (heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) same (semiconductor die dice chip ic (integrated adj circuit)) same (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) same	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:44
11	728	<pre>((thermally thermal) adj6 (isolated)) (heat with (sink spreader lid cover dissipate dissipation dissipated dissipated slug frame radiate radiating radiated)) and (semiconductor die dice chip ic (integrated adj circuit)) and (substrate board carrier pcb ((wiring printed circuit) adj "4" board)) and ((thermally thermal) adj6 (isolated))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 11:45

12	683	((heat with (sink spreader lid cover	USPAT;	2004/08/30
		dissipate dissipation dissipated	US-PGPUB;	11:45
		dissipated slug frame radiate radiating	EPO; JPO;	
		radiated)) and (semiconductor die dice	DERWENT;	
		chip ic (integrated adj circuit)) and	IBM TDB	į .
		(substrate board carrier pcb ((wiring	_	
		printed circuit) adj "4" board)) and		
		((thermally thermal) adj6 (isolated)))		
		not ((heat with (sink spreader lid cover	İ	
		dissipate dissipation dissipated		
		dissipated slug frame radiate radiating		
		radiated)) same (semiconductor die dice		
		chip ic (integrated adj circuit)) same		
		(substrate board carrier pcb ((wiring		
		printed circuit) adj "4" board)) same		
		((thermally thermal) adj6 (isolated)))		